

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10715641			
<b>Filing Date:</b>	18-Nov-2003			
<b>Title of Invention:</b>	Raised solder-mask-defined (SMD) solder ball pads for a laminate electronic circuit board			
<b>First Named Inventor/Applicant Name:</b>	Tz-Cheng Chiu			
<b>Filer:</b>	Yingsheng Tung/Jackie McBride			
<b>Attorney Docket Number:</b>	TI-36052 (1962-07500)			
Filed as Large Entity				
<b>Utility      Filing Fees</b>				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1020